

D101 zener used to extend max duty cycle clamp.

R101, C101 snubber used to limit rectifiers switching voltage spikes.

Q101, D102, R102 used for startup at 9.6V input.

Net Class

ClassName: HV Input

SW1	SWN	VINP
SWA	SWP	
SWB	VI1	
SWC	VIN	

Net Class

ClassName: Input

COMP	CSW	OUTB	RES	UVLO
CS	DCL	PGATE	SS	VCC
CSG	GND	RCIN	SYNC	
CSR	OUTA	REF	TIME	

Net Class

ClassName: HV Output

SNR	SWS
SNS	
SW2	
SWR	

Net Class

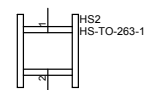
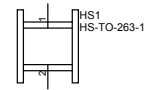
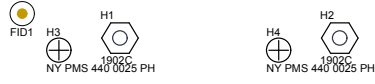
ClassName: Output

COMPA	IGND
COMPC	VO1
COMPK	VOUT
FB	

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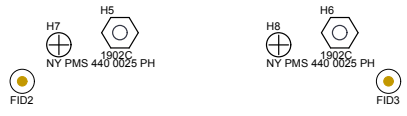
Number: PMP7892	Rev: A2	Designed for: Public Release	Mod Date: 1/28/2013
SVN Rev: Not in version control	Assembly Variant: [No Variations]	Project Title: LM5026 Isolated Active Clamp Forward	Sheet Title: LM5026 Active Clamp Forward
Drawn By:	Engineer: Robert Sheehan	File: PMP7892_REV A2.schDoc	Sheet: 1 of 2
		Contact: <a href="http://www.ti.com/support">http://www.ti.com/support</a>	Size: B

Revision History	
Revision	Notes
A	Initial design 12/17/2012
A1	Modify prototype 1/4/2013
A2	Change Transformer 1/26/2013



PCB Number: PMP7892  
PCB Rev: A

PCB LOGO  
Texas Instruments



LBL1  
PCB Label  
Size: 0.65" x 0.20"

ZZ1  
Label Assembly Note  
This Assembly Note is for PCB labels only

ZZ2  
Assembly Note  
These assemblies are ESD sensitive, ESD precautions shall be observed.

ZZ3  
Assembly Note  
These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

ZZ4  
Assembly Note  
These assemblies must comply with workmanship standards IPC-A-610 Class 2., unless otherwise specified.

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Drawn By:	File: PMP7892_REV A2_Hardware.SchDoc	Sheet 2 of 2	Size: B
Engineer: Robert Sheehan	Contact: <a href="http://www.ti.com/support">http://www.ti.com/support</a>		



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